

AN 1980-21388C [12] WPIDS
 TI Soldering material for external parts of watch - comprises gold-
 tin alloy of low soldering temperature and high corrosion
 resistance.
 DC M23 M26 S04
 PA (SUWA) SUWA SEIKOSHA KK
 CYC 1
 PI JP 55020403 A 19800213 (198012)*
 PRAI JP 1978-88713 19780720
 AB JP 55020403 A UPAB: 19930902
 A soldering material consists of Au 10-85 weight% and Sn 15-90 weight% and
 >=1
 of Ni 0.1-1 weight%, Cu 0.1-15 weight%, Ag 3-48
 weight%, P 0.2-15 weight%, Co 0.1-2 weight%, Ca 0.1-3 weight%, Mn
 0.1-3 weight%, Pt 0.1-5 weight%, Sb 0.1-64 weight%, Se 0.05-0.5 weight% and
 Te 0.05-2
 weight%.
 The Au-Sn base alloy has high corrosion
 resistance and low soldering temperature, nonsequestly softening of the
 external
 parts can be prevented and also strain relief annealing can be achieved in
 soldering with the soldering material. The melting point of the Au-
 Sn alloy of <85% of Au is <=500 degrees C, especially the
 eutectic alloy of Au 80% and Sn 20% has a melting point of 280 degrees C,
 at which brass, nickel, silver and stainless steel do
 not soften.

0.1-15 Cu
 0.1-2 Co
 0.1-1 Ni
 0.2-15 P
 3-48 Ag

 Sn